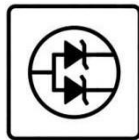
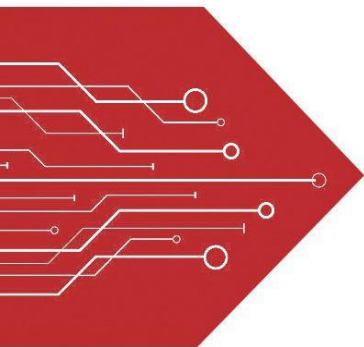


MSKSEMI

SEMICONDUCTOR



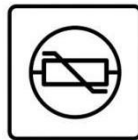
ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

Features

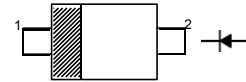
- Small plastic package suitable for surface mounted design
- High reliability with high surge current handling capability

Applications

- High speed switching

PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1 | Cathode |
| 2 | Anode |



SOD-323

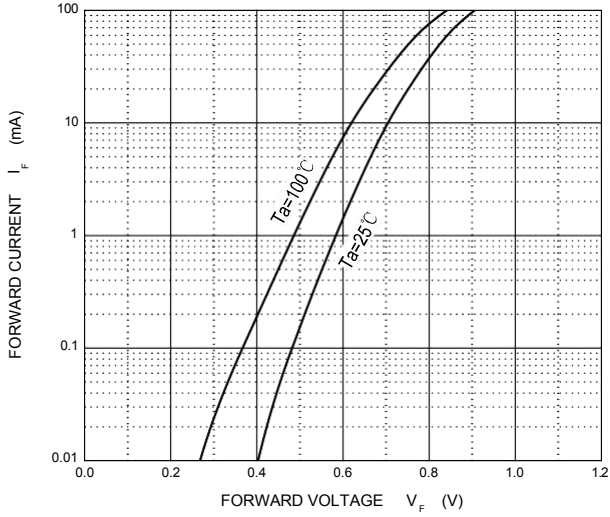
Absolute Maximum Ratings (T_a = 25 °C)

| Parameter | Symbol | Value | Unit |
|-----------------------------------|--------------------|---------------|------|
| Peak Reverse Voltage | V _{RM} | 90 | V |
| Reverse Voltage | V _R | 80 | V |
| Average Rectified Forward Current | I _{F(AV)} | 100 | mA |
| Peak Forward Current | I _{FM} | 225 | mA |
| Surge Forward Current (1 s) | I _{FSM} | 500 | mA |
| Junction Temperature | T _j | 150 | °C |
| Storage Temperature Range | T _{stg} | - 55 to + 150 | °C |

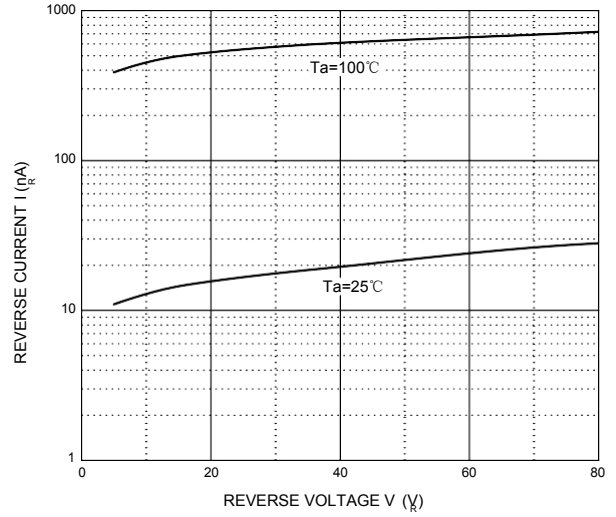
Electrical Characteristics (T_a = 25 °C)

| Parameter | Symbol | Max. | Unit |
|--|-----------------|------|------|
| Forward Voltage at I _F = 100 mA | V _F | 1.2 | V |
| Reverse Current at V _R = 80 V | I _R | 0.1 | μA |
| Capacitance between Terminals at V _R = 0.5 V, f = 1 MHz | C _T | 3 | pF |
| Reverse Recovery Time at V _R = 6 V, I _F = 10 mA, R _L = 100 Ω | t _{rr} | 4 | ns |

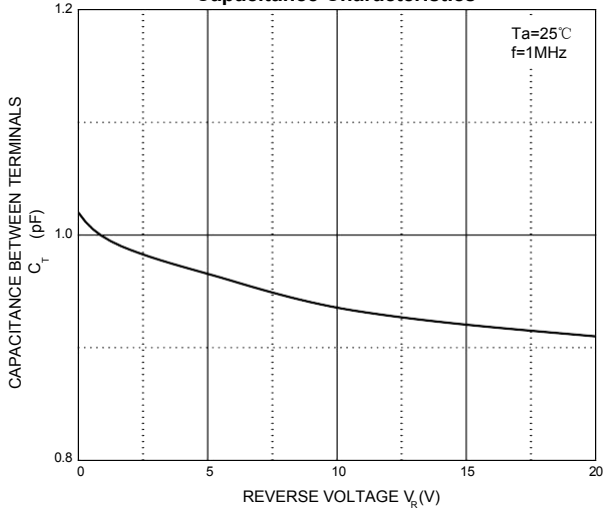
Forward Characteristics



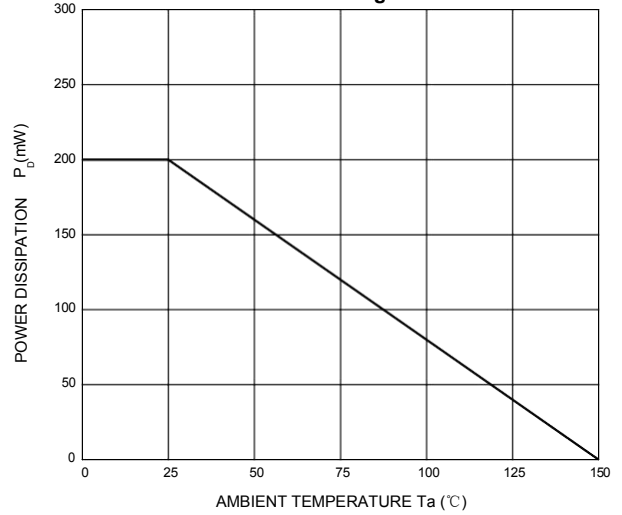
Reverse Characteristics



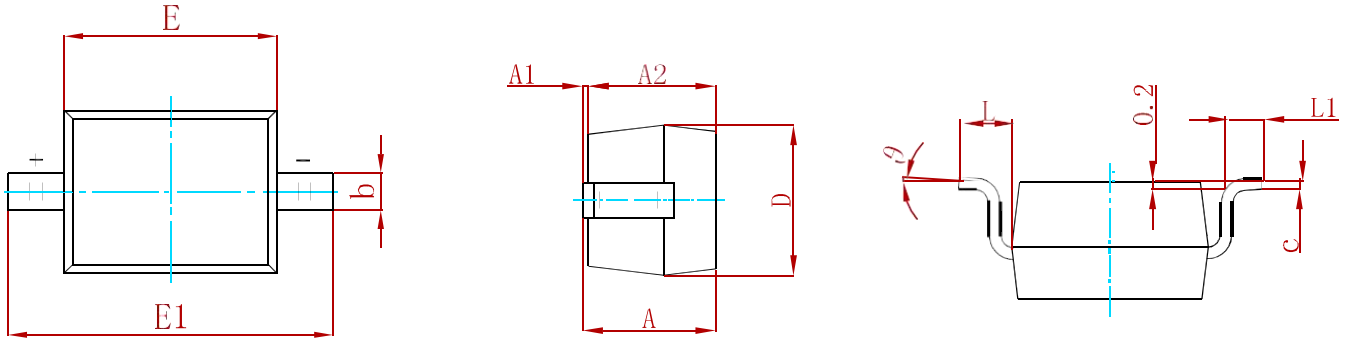
Capacitance Characteristics



Power Derating Curve

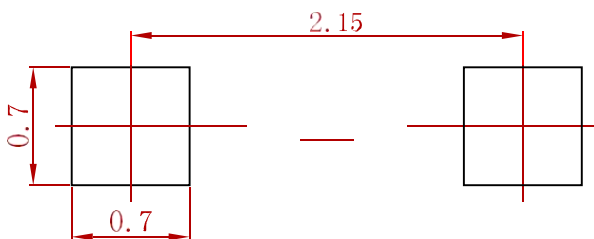


PACKAGE MECHANICAL DATA



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | | 1.000 | | 0.039 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 0.800 | 0.900 | 0.031 | 0.035 |
| b | 0.250 | 0.350 | 0.010 | 0.014 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 1.200 | 1.400 | 0.047 | 0.055 |
| E | 1.600 | 1.800 | 0.063 | 0.071 |
| E1 | 2.550 | 2.750 | 0.100 | 0.108 |
| L | 0.475 REF. | | 0.019 REF. | |
| L1 | 0.250 | 0.400 | 0.010 | 0.016 |
| θ | 0° | 8° | 0° | 8° |

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

| P/N | PKG | QTY |
|-----------|---------|------|
| 1SS355-MS | SOD-323 | 3000 |

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